January 7, 2025

NEWS RELEASE

VSP™ Electro-Deposited Copper Foil for High-Frequency Circuit Boards Production Capacity Enhanced

— Taiwan Plant capacity increased and production started at Malaysia Plant to increase capacity to 580 tons per month, an approximately 40% increase —

Mitsui Mining & Smelting Co., Ltd. (NOU Takeshi, President; hereinafter “Mitsui Kinzoku”) announces that it will increase its VSP™ electro-deposited copper foil for high-frequency circuit boards production capacity approximately 40%, from the current level to 580 tons per month following an increase in production capacity at the Taiwan Plant, where VSP™ electro-deposited copper is currently manufactured, and the commencement of production at the Malaysia Plant.

Mitsui Kinzoku’s VSP™ copper foil for high-frequency circuit boards has been used in servers, routers, switches and other high-performance communication infrastructure equipment since it greatly contributes to the reduction of transmission loss in printed circuit boards at high frequency signal bands. Currently, its demand significantly growing particularly for AI server-related applications. It is expected that further commercial expansion will be achieved in the future.

In these circumstances, the Taiwan Plant (Taiwan Copper Foil Co., Ltd.) improved productivity with its existing facilities to complete its expansion to a production capacity of 520 tons per month. It is already operating at this increased capacity. In addition, the Malaysia Plant (Mitsui Copper Foil (Malaysia) Sdn. Bhd.) will begin producing VSP™ by converting its existing facilities for conventional foil. Beginning in April 2025, it will operate at a production capacity of 60 tons per month.

After these steps, the total VSP™ production capacity of the two sites in Taiwan and Malaysia will be 580 tons per month. With an eye toward the further increase of production capacity to meet the growth of demand in the future, Mitsui Kinzoku will fully continue to meet the strong demand.

Mitsui Kinzoku will contribute to the realization of a sustainable society by implementing our its vision for 2030, “Building new businesses -and the future- with our material intelligence,” based on its purpose, “We promote the well-being of the world through a spirit of exploration and diverse technologies.”

■ VSP™ production capacity (for reference)

	Before enhancements	**After enhancements**	Remarks
Taiwan Copper Foil	420 t / month	**520 t / month**	Enhancements completed and operations started
Mitsui Copper Foil (Malaysia)	0 t / month	**60 t / month**	Operations to start from April 2025
Total	420 t / month	**580 t / month**	

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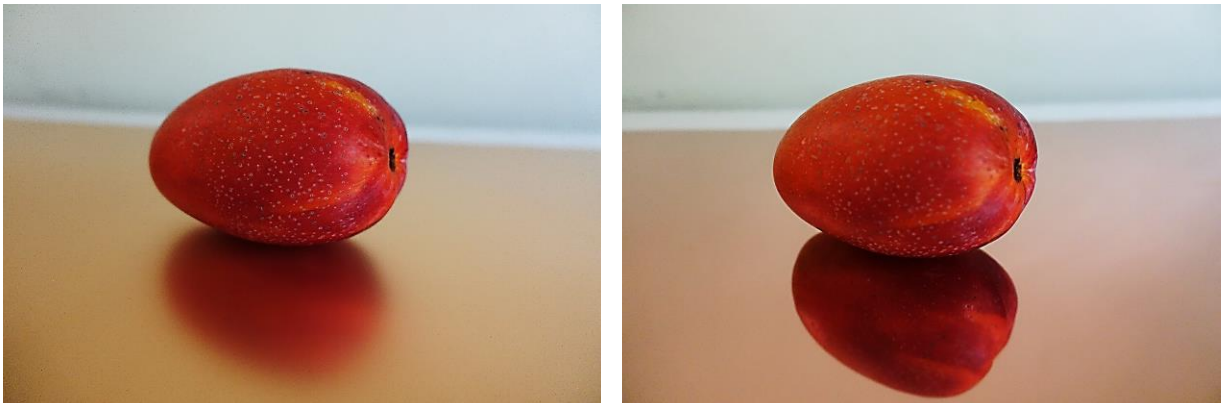

Conventional copper foil

VSP™

Photo: A reflection of an apple mango in a copper foil surface

* VSP™ is characterized by its outstanding surface smoothness comparable to that of a mirror.

(Reference)

Main functions of VSP™:

It is a copper foil for high-frequency circuit boards for communication infrastructure devices, including servers, switches, routers and base stations.